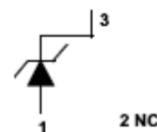


FEATURES

- ◆ Planar Die Construction.
- ◆ 350mw Power Dissipation.
- ◆ Zener Voltages From 2.4V -51V
- ◆ Ideally Suited For Automated Assembly Processes



**CONNECTION
DIAGRAM**



APPLICATIONS

- ◆ 350Mw Surface mount zener diode

MAXIMUM RATING @ Ta=25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Forward Voltage@I _F =10mA	V _F	0.9	V
Power Dissipation	P _d	350	mW
Thermal Resistance, Junction to Ambient Air	R _{θJA}	357	°C/W
Operating and Storage Temperature Range	T _J , T _{stg}	-65 to+150	°C

Notes: 1. Valid provided that device terminals are kept at ambient temperature.

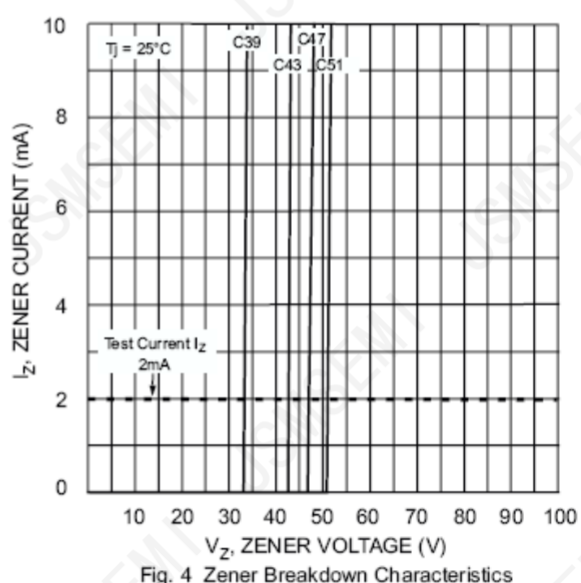
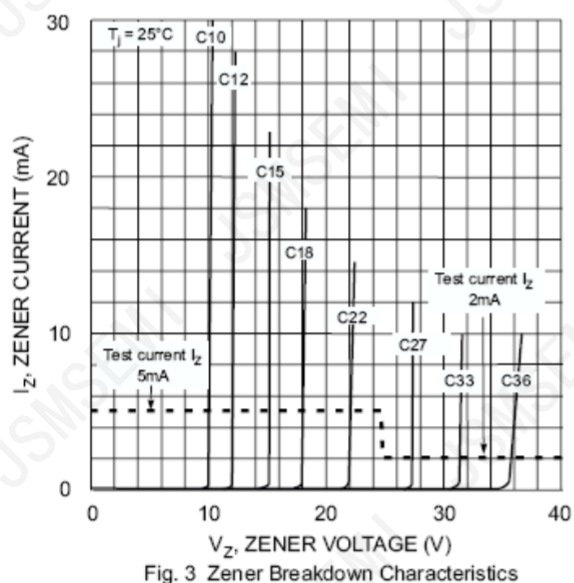
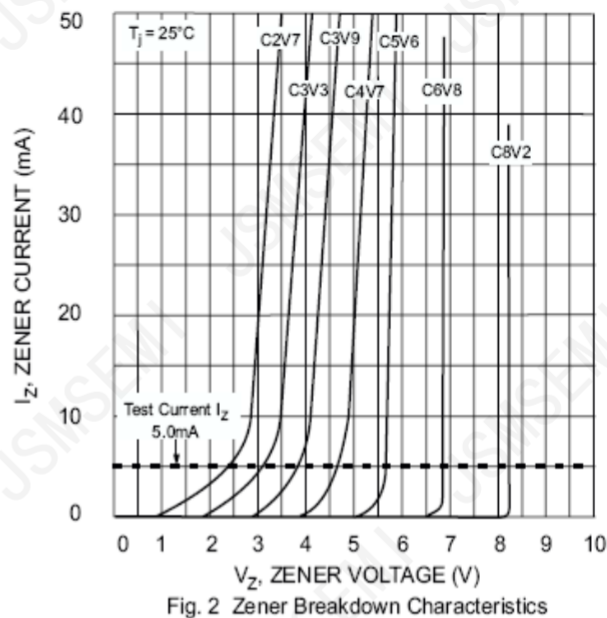
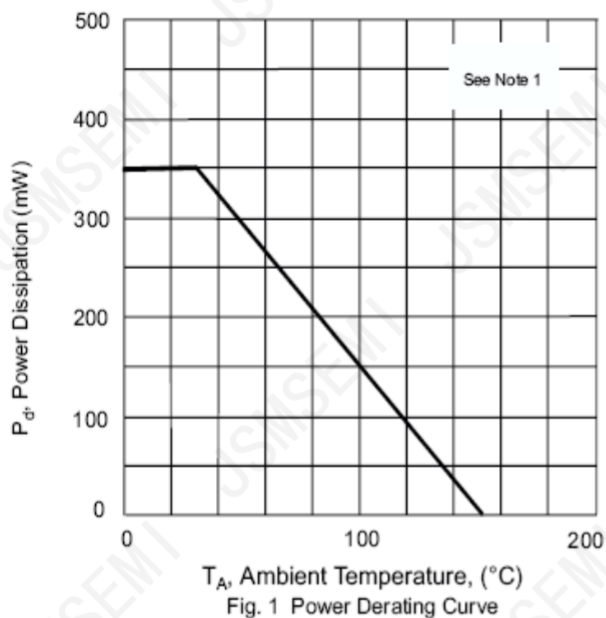
2. Tested with pulses, 300μs pulse width, period = 5ms.

3. f = 1KHz.

ELECTRICAL CHARACTERISTICS@ Ta=25°C unless otherwise specified

Type Number	Marking Code	Zener Voltage Range				Maximum Zener Impedance			Maximum Reverse Current		Typical Temperature Coefficient @I _{ZT} mV/°C	
		V _Z @I _{ZT}				I _{ZT}	Z _{ZT} @I _{ZT}	Z _{ZK} @I _{ZK}	I _R	V _R	Min	Max
		Nom(V)	Min(V)	Max(V)	(mA)	(Ω)	(Ω)	(mA)	(μA)	(V)		
BZX84-C16 ,215-JSM	Y5	16	15.3	17.1	5.0	40	200	1.0	0.1	11.2	10.4	14.0

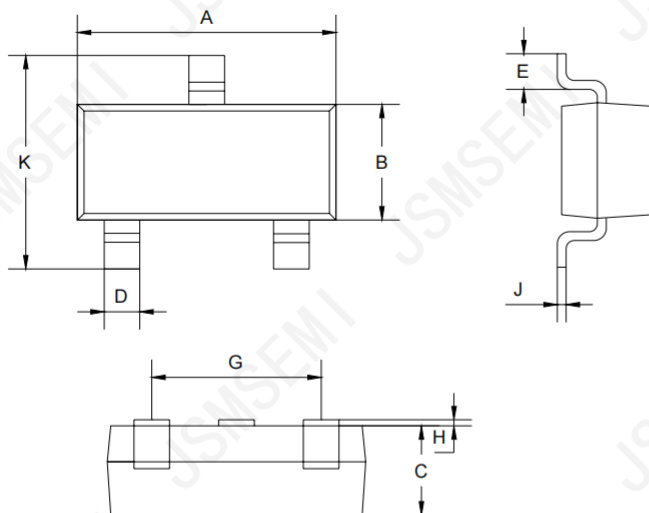
TYPICAL CHARACTERISTICS @ $T_a=25^\circ\text{C}$ unless otherwise specified



PACKAGE OUTLINE

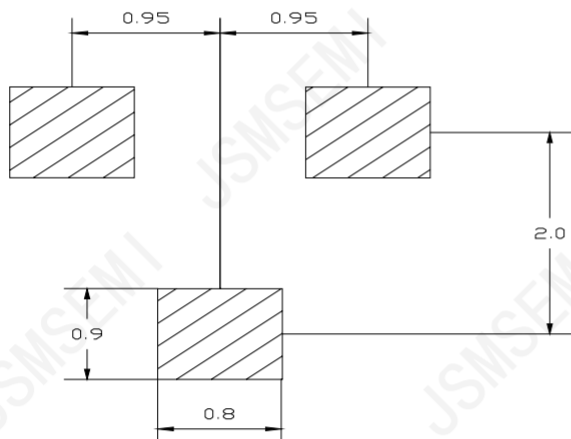
Plastic surface mounted package

SOT-23



SOT-23		
Dim	Min	Max
A	2.85	2.95
B	1.25	1.35
C	1.0Typical	
D	0.37	0.43
E	0.35	0.48
G	1.85	1.95
H	0.02	0.1
J	0.1Typical	
K	2.35	2.45
All Dimensions in mm		

SOLDERING FOOTPRINT



Unit : mm

PACKAGE INFORMATION

Device	Package	Shipping
BZX84-C16,215-JSM	SOT-23	3000/Tape&Reel

Revision History

Rev.	Change	Date
V1.0	Initial version	2/23/2024

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